

2N681-2N692, 2N5204-2N5207

SILICON CONTROLLED RECTIFIER

FEATURES

- Available as "HR" (high reliability) screened per MIL-PRF-19500, JANTX level. Add "HR" suffix to base part number.
- Available as non-RoHS (Sn/Pb plating), standard, and as RoHS by adding "-PBF" suffix.

MAXIMUM RATINGS

| Rating | Symbol | 2N681-2N692 | 2N5204-2N5207 | Unit |
|--|---------------------|-------------|---------------|------------------|
| RMS On-State Current | I _{T(RMS)} | 25 | 35 | Α |
| Average On-State Current | I _{T(AV)} | 16 | 22 | Α |
| @ T _C | T _C | -65 to +65 | -40 to +40 | °C |
| Peak One Cycle Surge @ 50 Hz | 1 | 145 | 285 | Α |
| Peak One Cycle Surge @ 60 Hz | I _{TSM} | 150 | 300 | Α |
| Fusing @ 50 Hz | l²t | 103 | 410 | A ² s |
| Fusing @ 60 Hz | 1-1 | 94 | 375 | A-S |
| Gate Current to Trigger | I _{GT} | 40 | 40 | mA |
| Typical Critical dv/dt Exponential to VDRM | dv/dt | - | 100 | V/µs |
| Critical Rate of Rise | di/dt | 75-100 | 100 | A/μs |
| Junction Temperature | Tı | -65 to 125 | -65 to 125 | °C |
| Storage Temperature | T _{stg} | -65 to 150 | -65 to 150 | °C |

VOLTAGE RATINGS (Applied gate voltage zero or negative)

| Part Number | V _{RRM} , V _{DRM} Maximum Repetitive Peak Reverse and Off-State Voltage (V) | V_{RSM} Maximum Non-Repetitive Peak Reverse Voltage $t_p \leq 5 \ ms \ (V)$ |
|-------------|---|---|
| | T _J = -65 to +125°C | T _J = -65 to +125°C |
| 2N681 | 25 | 35 |
| 2N682 | 50 | 75 |
| 2N683 | 100 | 150 |
| 2N685 | 200 | 300 |
| 2N687 | 300 | 400 |
| 2N688 | 400 | 500 |
| 2N689 | 500 | 600 |
| 2N690 | 600 | 720 |
| 2N691 | 700 | 840 |
| 2N692 | 800 | 960 |
| | T _J = -65 to 125°C | T _J = -65 to 125°C |
| 2N5204 | 600 | 720 |
| 2N5205 | 800 | 960 |
| 2N5206 | 1000 | 1200 |
| 2N5207 | 1200 | 1440 |



2N681-2N692, 2N5204-2N5207

SILICON CONTROLLED RECTIFIER

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise specified)

| Symbol | Characteristics | 2N681-2N692 | 2N5204-2N5207 | Units | Condit | ions |
|---------------------|---|---|---|------------------|--|---|
| I _{T(RMS)} | Maximum RMS On-State Current | 25 | 35 | Α | | |
| I _{T(AV)} | Maximum Average On-State Current | 16 | 22 | А | 180° half sine wa | ve conduction |
| | @ T _C = | -65 to +65 | -40 to +40 | °C | | |
| | | 145 | 285 | | 50 Hz half cycle sine wave or 6 ms rectangular pulse | Following any rated load |
| I _{TSM} | Maximum Peak One Cycle, | 150 | 300 | - A | 60 Hz half cycle sine wave or 5 ms rectangular pulse | condition and with rated V _{RRM} applied following surge |
| | Non-Repetitive Surge Current | 170 | 340 | A | 50 Hz half cycle sine wave or 6 ms rectangular pulse | Same conditions as above except |
| | | 180 | 355 | | 60 Hz half cycle sine wave or 5 ms rectangular pulse | with V _{RRM} applied following surge = 0 |
| | | 103 | 410 | | t = 10 ms | Rated V _{RRM} applied |
| l²t | t Maximum I ² t Capability, for Fusing | 94 | 375 | A ² s | t = 8.3 ms | following surge, initial T」= 125°C |
| | Maximum 12t Canability for | 145 | 580 | | t = 10 ms | V _{RRM} = 0 following |
| l²t | Maximum I ² t Capability for Individual Device Fusing | 135 | 530 | A ² s | t = 8.3 ms | surge, initial T _J = 125°C |
| I²√t | Maximum I ² Vt Capability for Individual Device Fusing (1) | 1450 | 5800 | A²√s | $t = 0.1$ to 10ms initial $T_J \le 125$ °C, V_{RRM} following surge = 0 | |
| V тм | Maximum Peak On-State Voltage | 2 | 2.3 | V | T ₁ = 25°C, I _{T(AV)} = 16A(50A peak) – 2N681 I _{T(AV)} = 22A (70A) peak – 2N5204 | |
| I _H | Maximum Holding Current | 20 @ 25°C | 200 @-40°C | mA | Anode supply = 24V, initial I_T = 1.0A | |
| BLOCKING | | | | | | |
| dv/dt | Minimum Critical Rate of Rise of | 100 typical 100 V/μs exponential to 100% rated V _{DRM} | T _J = 125°C exponential to 100% rated V _{DRM} | | | |
| av/at | Off-State Voltage | 250 typical | 250 | | T _J = 125°C exponential to 67% rated V _{DRM} | |



2N681-2N692, 2N5204-2N5207

SILICON CONTROLLED RECTIFIER

| Symbol | Characteristics | 2N681-2N692 | 2N5204-2N5207 | Units | Conditions |
|---|--|---|-----------------------------------|-------|---|
| I _R ⁽⁻⁾ & I _D ⁽⁻⁾ | Maximum Reverse and Off-State | I _{R(AV)} & I _{D(AV)} | I _{RM} & I _{DM} | mA | |
| | Current | (average values) | (peak values) | | |
| | V _{RRM} & V _{DRM} = | - | - | | |
| | 25 to 150V | 6.5 | - | | |
| | 200 & 250V | 6.0 | - | | |
| | 300V | 5.0 | - | | |
| | 400V | 4.0 | - | | T _J = 125°C, gate open circuited |
| | 500V | 3.0 | - | | |
| | 600V | 2.5 | 3.3 | | |
| | 700V | 2.25 | - | | |
| | 800V | 2.0 | 2.5 | | |
| | 1000V | - | 2.0 | | |
| | 1200V | - | 1.7 | | |
| SWITCHING | | | | l | |
| t _d | Typical Delay Time | 1 | 1 | μs | T_{C} = 25°C, V_{DM} = rated V_{DRM} , I_{TM} = 10A dc resistive circuit. Gate pulse: 10 V, 40Ω source, t_{p} = 6μ s, t_{r} = 0.1μ s |
| | Maximum Non-Repetitive Rate of Rise of Turned-On Current V _{DM} = 25 to 600 V | 100 | - | A/μs | $T_{C}=125^{\circ}\text{C, V}_{DM}=\text{ rated V}_{DRM}, I_{TM}=2\text{ x}$ di/dt, gate pulse: 20V, 15 Ω , $t_{p}=6\mu s$, |
| di/dt | V _{DM} = 700 to 800 V | 75 | - | | t _r = 0.1 μs maximum |
| | | - | 100 | | T_C = 125°C, V_{DM} = 600V, I_{TM} = 200A @ 400Hz max. Gate pulse: 20V, 15Ω, t_p = 6μs, t_r = 0.1μs max. |
| TRIGGERING | | | | | |
| P _{GM} | Maximum Peak Gate Power | 5 | 60 | W | $t_p \le 5ms - 2N681$ $t_p \le 500\mu s - 2N5204$ |
| P _{G(AV)} | Maximum Average Gate Power | 0.5 | 0.5 | W | |
| I _{GM} | Maximum Peak Positive Gate Current | 2 | 2 | А | |
| +V _{GM} | Maximum Peak Positive Gate Voltage | 10 | - | V | |
| -V _{GM} | Maximum Peak Negative Gate Voltage | 5 | 5 | V | |
| I _{GT} | Maximum Required DC Gate Current to Trigger | 80 | 80 | mA | T _C = min rated value. Max. required gate trigger current is the lowest value which will trigger all units with 6V anode to cathode |
| 31 | | 40 | 40 | | T _C = 25°C |
| | | 18.5 | 20 | | T _C = 125°C |
| | Typical DC Gate Current to Trigger | 30 | 30 | | T _C = 25°C, 6V anode to cathode |



2N681-2N692, 2N5204-2N5207

SILICON CONTROLLED RECTIFIER

| Symbol | Characteristics | 2N681-2N692 | 2N5204-2N5207 | Units | Conditions |
|-----------------|--|-------------|---------------|-------|--|
| V _{GT} | Maximum Required DC Gate Voltage to Trigger | 3 | 3 | V | T_{C} = -65°C. Max. required gate trigger voltage is the lowest value which will trigger all units with 6V anode to cathode |
| | | 2 | 2 | | T _C = 25°C |
| | Typical DC Gate Voltage to Trigger | 1.5 | 1.5 | | T _C = 25°C 6V anode to cathode |
| V _{GD} | Maximum DC Gate Voltage Not to Trigger | 0.25 | 0.25 | V | T_{C} = 125°C. Max. gate voltage not to trigger is the maximum value which will not trigger any unit with rated V_{DRM} anode to cathode |

Note 1: I^2t for time $t_x \approx I^2\sqrt{t} \cdot \sqrt{t_x}$

THERMAL -MECHANICAL CHARACTERISTICS

| Symbol | Characteristics | 2N681-2N692 | 2N5204-2N5207 | Units | Conditions |
|-------------------|--|-------------|---------------|---------|---|
| Тл | Operating Junction Temperature Range | -65 to 125 | -40 to 125 | °C | |
| T _{stg} | Storage Temperature Range | -65 to 125 | -40 to 125 | °C | |
| R _{thJC} | Maximum Internal Thermal Resistance, Junction to Case | 1.5 | 1.5 | °C/W | DC operation |
| R _{thCS} | Thermal Resistance, Case to Sink | 0.35 | 0.35 | °C/W | Mounting surface smooth, flat and greased |
| | | 20 (27.5) | | lbf∙in | Lubricated threads (non-lubricated threads) |
| | Mounting Torque to nut ±10% | 0.23 (0.32) | | kgf · m | |
| | | 2.3 | (3.1) | N·m | tilleausj |
| | | 25 | | lbf∙in | |
| | Mounting Torque to Device | 0.29 | | kgf · m | Lubricated threads |
| | | 2.8 | | N · m | |
| wt | Approximate Weight | 14 (0.49) | 14 (0.5) | g (oz.) | |

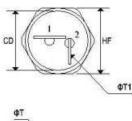


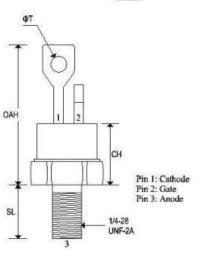
2N681-2N692, 2N5204-2N5207

SILICON CONTROLLED RECTIFIER

MECHANICAL CHARACTERISTICS

| Case | TO-48A |
|---------|---------------|
| Marking | Alpha-numeric |
| Pin out | See below |





| | TO-48A | | | | | |
|-----|--------|-------|-----------------|-------|--|--|
| | Inc | hes | Millimeters | | | |
| | Min | Max | Min | Max | | |
| CD | | 0.563 | 2. 2 (2) | 14.30 | | |
| CH | - 2 | 0.579 | | 14.70 | | |
| HF | 0.543 | 0.559 | 13.80 | 14.20 | | |
| OAH | | 1.299 | * | 33.00 | | |
| SL | 0.425 | 0.453 | 10.80 | 11.50 | | |
| ФТ | 0.125 | 0.165 | 3.17 | 4.20 | | |
| ФТ1 | 0.043 | 0.075 | 1.10 | 1.91 | | |

Note: Contour and angular orientation of terminals 1 and 2 with respect to hex portion and to each other are optional.



2N681-2N692, 2N5204-2N5207

SILICON CONTROLLED RECTIFIER

2N681 Series

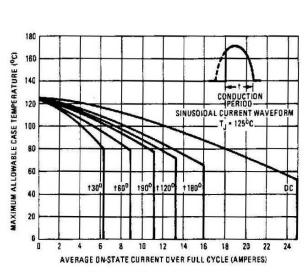


Fig. 1 — Maximum Allowable Case Temperature Vs. Average On-State Current, 2N681 Series

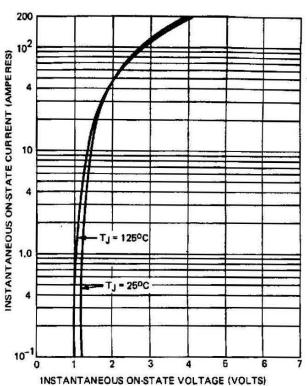


Fig. 2 — Maximum On-State Voltage Vs. Current, 2N681 Series



2N681-2N692, 2N5204-2N5207

SILICON CONTROLLED RECTIFIER

2N681 Series

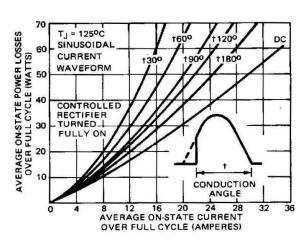


Fig. 3 — Maximum Low Level On-State Power Loss Vs. Current (Sinusoidal Current Waveform), 2N681 Series

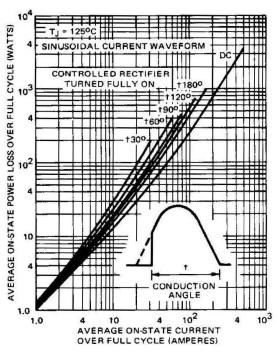


Fig. 4 — Maximum High Level On-State Power Loss Vs. Current (Sinusoidal Current Waveform), 2N681 Series

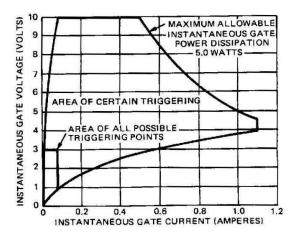


Fig. 5 - Gate Characteristics, 2N681 Series

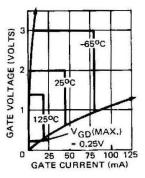


Fig. 5A — Area of All Possible Triggering Points Vs. Temperature 2N681 Series



2N681-2N692, 2N5204-2N5207

SILICON CONTROLLED RECTIFIER

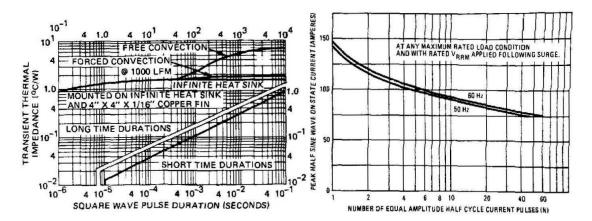


Fig. 6 — Maximum Transient Thermal Impedance, Junction to Case, Vs. Pulse Duration, 2N681 Series

Fig. 7 — Maximum Non-Repetitive Surge Current, Vs. Number of Current Pulses, 2N681 Series

2N5204 Series

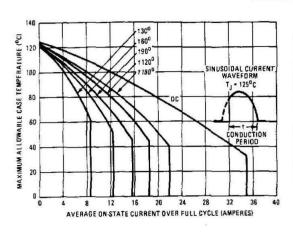


Fig. 8 — Maximum Allowable Case Temperature Vs. Average On-State Current (Sinusoidal Current Waveform), 2N5204 Series

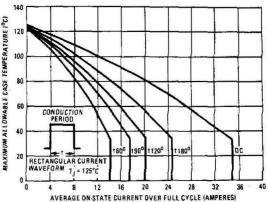


Fig. 9 — Maximum Allowable Case Temperature
Vs. Average On-State Current
(Rectangular Current Waveform), 2N5204 Series



2N681-2N692, 2N5204-2N5207

SILICON CONTROLLED RECTIFIER

2N5204 Series

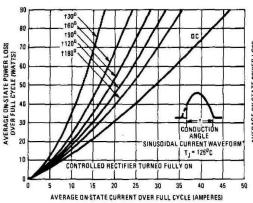


Fig. 10 — Maximum Low-Level On-State Power Loss Vs. Average On-State Current (Sinusoidal Current Waveform), 2N5204 Series

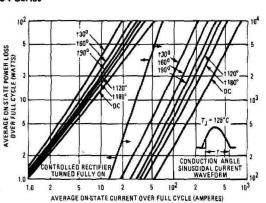


Fig. 11 — Maximum High-Level On-State Power Loss Vs. Average On-State Current (Sinusoidal Current Waveform), 2N5204 Series

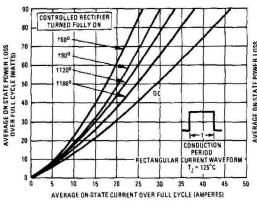


Fig. 12 — Maximum Low-Level On-State Power Loss
Vs. Average On-State Current
(Rectangular Current Waveform), 2N5204 Series

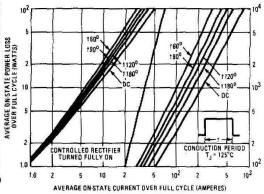


Fig. 13 — Maximum High-Level On-State Power Loss Vs. Average On-State Current (Rectangular Current Waveform), 2N5204 Series

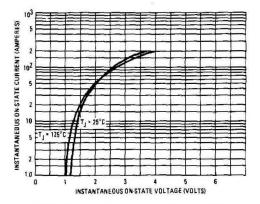


Fig. 14 — Maximum Instantaneous On-State Voltage Vs. Instantaneous On-State Current, 2N5204 Series

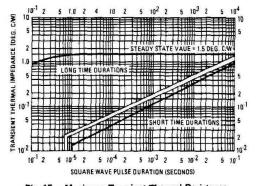


Fig. 15 — Maximum Transient Thermal Resistance, Junction to Case, Vs. Pulse Duration, 2N5204 Series